New Product Profile

September 2008

" Customers don't come to us to be sold. They come to us for solutions for their interconnect problems. "

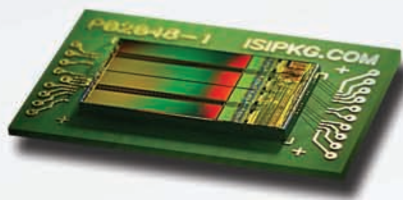
Bill Miller, ISI President & CEO

IC Packaging Solution

Concept & Feasibility | Design | Prototype & Qualification | Bare Die Assembly | Advanced SMT | Module Interconnect | Module Packaging | Test

Challenge:

A large industrial OEM experienced field failures on a critical control board utilized in a high vibration, vehicle environment. The root cause was determined to be solder joint failures on a Flash memory chip, attributed to the Alloy 42 material of the TSOP package leads. No alternative off-the shelf TSOPs were available, and a re-spin of the control board was too costly and time consuming.



Wirebond

Encapsulate

Flexframe TM

Solution:

ISI promptly designed a package to meet the customer's reliability requirements. The package houses a 1G NAND flash die and routes the signals to a 48 TSOP footprint using an ISI Flexframe constructed from Phosphor/Bronze leads. The die is wirebonded to a substrate then encapsulated. ISI's ability to design, manufacture and assemble the package and interconnect allowed the customer to continue shipping their product without any delays.

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